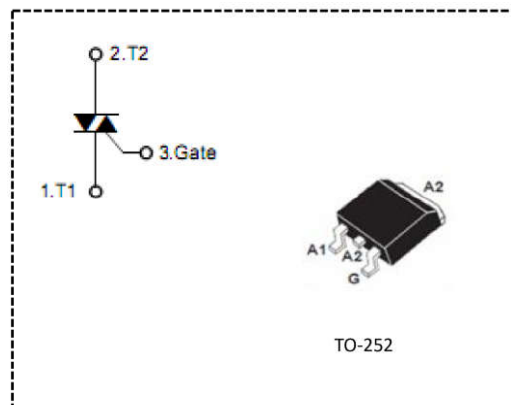


## ◆ 用途

主要用于调光、调温等调压电路，微波炉、洗衣机、电风扇、饮水机、夜明灯等家电的控制电路及用于交流相控、斩波器、逆变器、变频器和固态继电器等电路中

## ◆ 特征

采用先进的玻璃钝化工艺，较低的通态压降，高的可靠性、稳定性



## ◆ 极限值

名 称	符 号	规范值	单 位	测试条件
重复峰值阻断电压	$V_{DRM}$	600/800	V	$I_{DRM}=20\mu A$
通态电流	$I_{T(RMS)}$	4	A	正弦波 180°
浪涌电流	$I_{TSM}$	45	A	正弦波, 60Hz
结温	$T_j$	125	°C	
贮存温度	$T_{stg}$	-40~150	°C	

## ◆ 电特性

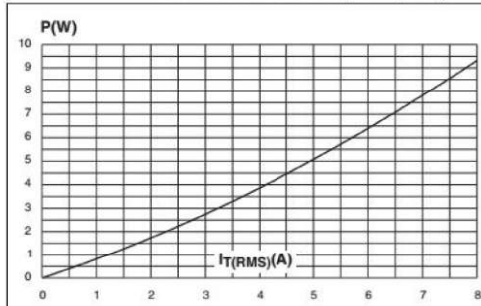
名 称	符 号	测 试 条 件	Min	Max	单位
通态电压	$V_{TM}$	$I_T=10A$	----	1.65	V
维持电流	I	$V_D=12V, I_{GT}=100mA$	----	10	mA
	II		----	10	
门极触发电流	I	$I_{GT}$	$T2(+), G(+)$	$V_D=12V, R_L=100\Omega$	10
	II				10
	III				10
	IV				----
门极触发电压	I	$V_{GT}$	$T2(+), G(+)$	$V_D=12V, R_L=100\Omega$	1.5
	II				1.5
	III				1.5
	IV				----
断态电压临界上升率	$dV/dt$	$V_D=0.66 \times V_{DRM}$ $T_J=125^\circ C$ Exponential waveform, Gate open	50		V/ $\mu s$
通态电流临界上升率	$dI/dt$	$T_J=125^\circ C, f=120Hz, I_G=2 \times I_{GT},$ $tr \leq 120ns$		50	A/ $\mu s$
断态电流临界上升率	$dI/dt \odot$	$V_{DM}=400V$ $T_J=125^\circ C$ $I_{T(RMS)}=4A$ $dV/dt=0.1V/\mu s$ Gate open	5		A/ms
热阻	$R_{th(j-c)}$	结到外壳		2.0	°C/W
	$R_{th(j-a)}$	结到环境		70	

## ◆ 产品包装

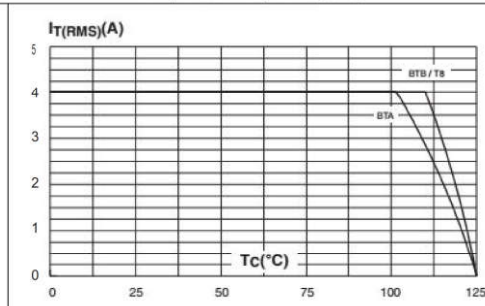
封装形式	数 量	包装材质
TO-252	2500/盘、25000/箱	盘/箱

◆ 特性数据

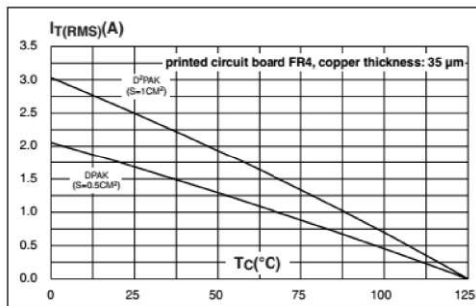
**Figure 1. Maximum power dissipation versus rms on-state current (full cycle)**



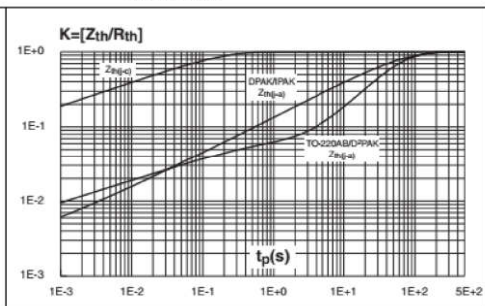
**Figure 2. On-state rms current versus case temperature (full cycle)**



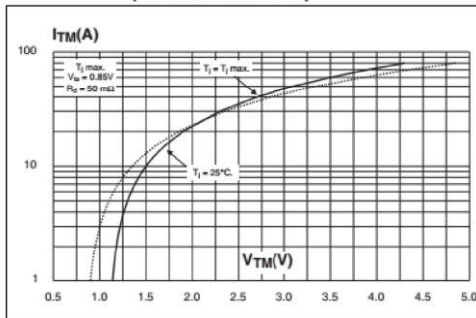
**Figure 3. On-state rms current versus ambient temperature (full cycle)**



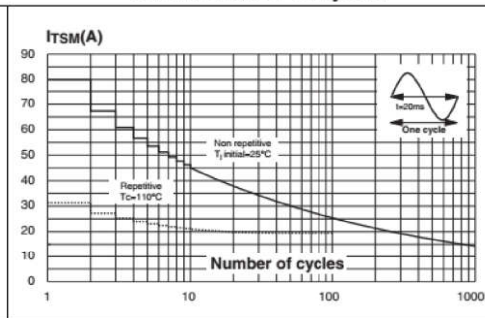
**Figure 4. Relative variation of thermal impedance versus pulse duration**



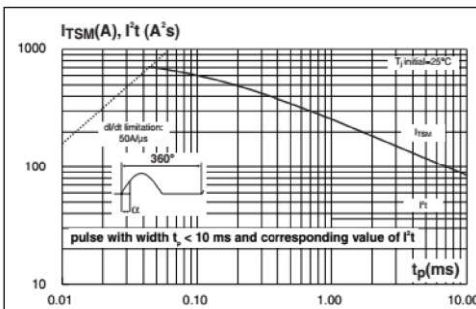
**Figure 5. On-state characteristics (maximum values)**



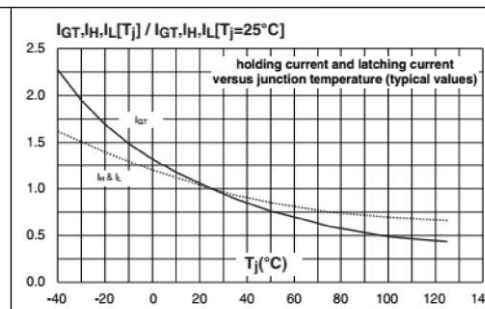
**Figure 6. Surge peak on-state current versus number of cycles**



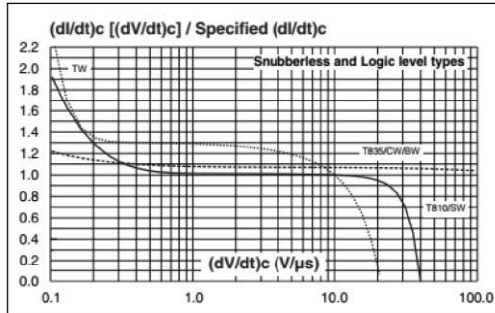
**Figure 7. Non-repetitive surge peak on-state current for a sinusoidal**



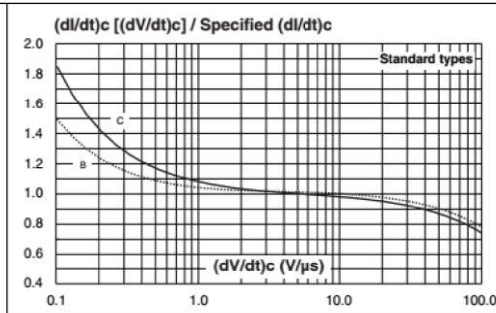
**Figure 8. Relative variation of gate trigger current**



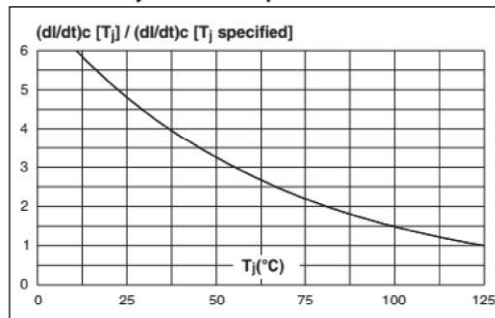
**Figure 9. Relative variation of critical rate of decrease of main current versus  $(dV/dt)_c$  (typical values)**



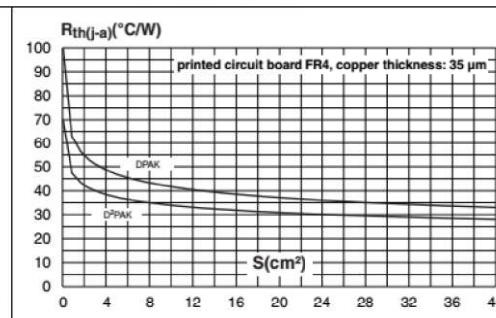
**Figure 10. Relative variation of critical rate of decrease of main current versus  $(dV/dt)_c$  (typical values)**



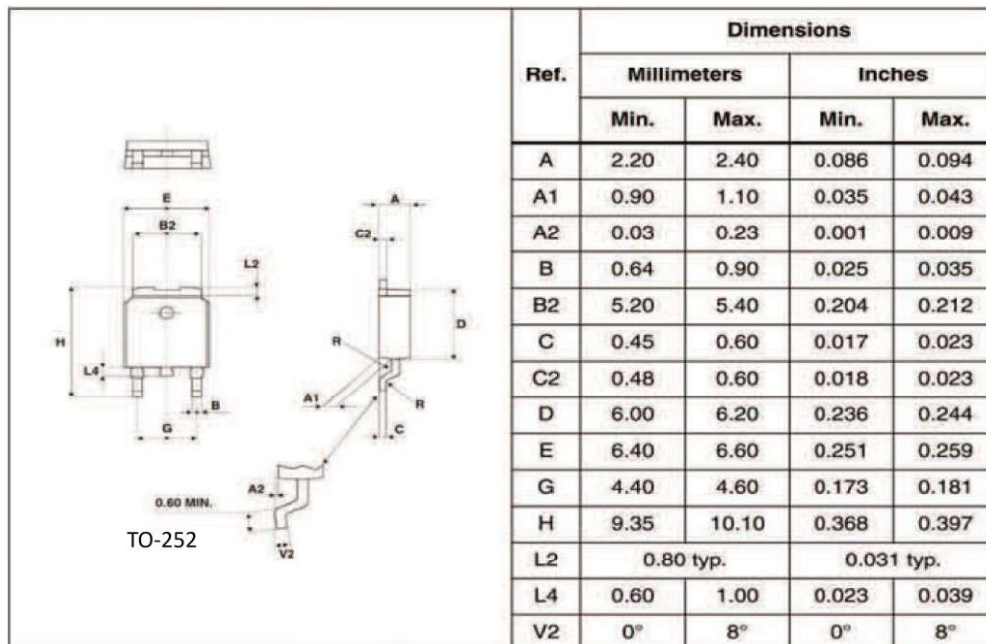
**Figure 11. Relative variation of critical rate of decrease of main current versus junction temperature**



**Figure 12. DPAK and D<sup>2</sup>PAK thermal resistance junction to ambient versus copper surface under tab**



◆ 产品尺寸



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